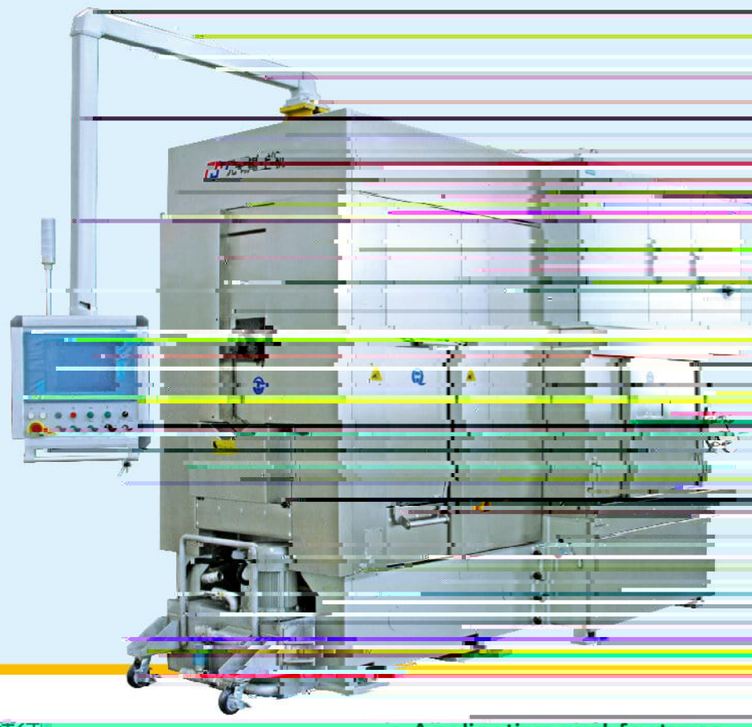
WSK000

蓝宝石切片机

WSK000 Sapphire Slicing Machine



设备用途与性能特点

- 本机床适于各种硬脆材料（硅、玻璃、陶瓷、蓝宝石晶体等）的切割硅、锗、石英玻璃、陶瓷、蓝宝石晶体等。
- 机床所有电器元件均采用国际知名品牌，保证机床的稳定性。
- 采用西门子摆动技术的一体化PC和15"触摸屏。
- 电控柜配备独立温控系统，保证[illegible]。
- 设备具备摇摆功能，对支架刚性与张紧力的精确控制能够[illegible]能，缩短了切割时间，并提高了晶片的质量。
- 滑轮数量最少化设计（双向摆动），减少钢线切割的弯折[illegible]

Applications and features

- The machine is used for [illegible] sapphire, silicon, germanium, quartz glass, ceramics, sapphire crystals, etc.
- All electrical components apply [illegible] brands to ensure the stability of the machine.
- Apply integrated PC of SIEMENS swing technology and 15" touch screen.
- The electric control cabinet is [illegible] sensor always to ensure the normal operation of [illegible].
- The equipment has a swing function, and the [illegible] function unit optimizes the performance of diamond wire cutting [illegible] shortens the cutting time and improves the quality of the wafer.
- Minimal design number of pulleys (two-way swing), reduces wire distortion and fatigue.

技术规格参数 Specifications and Technical Parameters

规格 Specification	Ø[illegible] (max.)
长度 Length	500mm
厚度 Thickness	≥0.2mm

主要参数 Main parameter

导轮直径 Guide wheel diameter	220mm
导轮轴距 Guide wheelbase	440mm
导轮长度 Guide wheel length	999mm
[illegible]	[illegible]
切割速率 Feed rate	0.01mm-2000mm/min
摇摆角度 Swinging angle	±32°
切割方向 Cutting direction	[illegible]
存储线面 Storage wire [illegible]	[illegible]
[illegible]	[illegible]

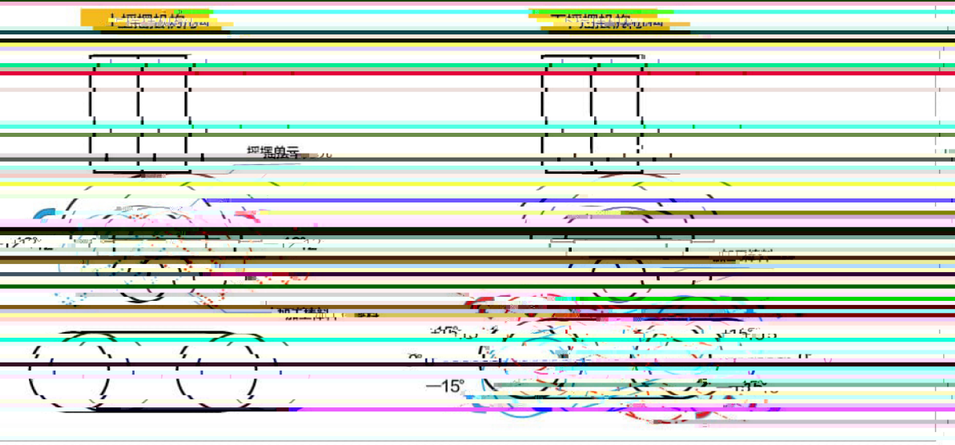
能源 Energy

电源连接 Power connection	[illegible]
[illegible]	[illegible]
冷却水温 Cooling water	12～17℃

外形尺寸 Machine size

机床外形尺寸（长×高×宽） Equipment size (L*W*H)	4600×2[illegible]×2[illegible]mm
机床重量 Weight	~12000kg

示意图 Sketch



由于产品不断[illegible]，本[illegible]
As products are [illegible]
modification without notification, we [illegible]